

# IGBT - Field Stop, Trench With Soft Fast Recovery Diode 650 V, 120 A FGY120T65SPD-F085

#### **Features**

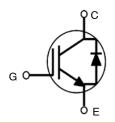
- Very Low Saturation Voltage :  $V_{CE(sat)} = 1.5 \text{ V(Typ.)}$  @  $I_C = 120 \text{ A}$
- Maximum Junction Temperature :  $T_I = 175^{\circ}C$
- Positive Temperature Co-efficient
- Tight Parameter Distribution
- High Input Impedance
- 100% of the Parts are Dynamically Tested
- Short Circuit Ruggedness > 6 μs @ 25°C
- Copacked with Soft, Fast Recovery Extremefast Diode
- AEC-Q101 Qualified and PPAP Capable
- This is a Pb-Free Device

#### **Benefits**

- Very Low Conduction and Switching Losses for a High Efficiency Operation in Various Applications
- Rugged Transient Reliability
- Outstanding Parallel Operation Performance with Balance Current Sharing
- Low EMI

#### **Applications**

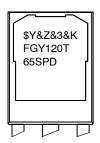
- Traction Inverter for HEV/EV
- Auxiliary DC/AC Converter
- Motor Drives
- Other Power-train Applications Requiring High Power Switch





TO-247-3LD CASE 340CU

#### **MARKING DIAGRAM**



\$Y = onsemi Logo

&Z = Assembly Plant Code

&3 = Data Code (Year & Week)

&K = Lot

FGY120T65SPD= Specific Device Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Description		Ratings	Units	
$V_{CES}$	Collector to Emitter Voltage	Collector to Emitter Voltage		V	
VG <sub>ES</sub>	Gate to Emitter Voltage		±20	V	
	Transient Gate to Emitter Voltage		±30	V	
I <sub>C</sub>	Collector Current (Note 1)	@ T <sub>C</sub> = 25°C	240	Α	
	Collector Current	@ T <sub>C</sub> = 100°C	220	Α	
I <sub>Nominal</sub>	Nominal Current		120	Α	
I <sub>CM</sub>	Pulsed Collector Current		378	Α	
I <sub>F</sub>	Diode Forward Current (Note 1)	@ T <sub>C</sub> = 25°C	240	Α	
	Diode Forward Current	@ T <sub>C</sub> = 100°C	188	Α	
$P_{D}$	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	882	W	
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	441	W	
SCWT	Short Circuit Withstand Time	@ T <sub>C</sub> = 25°C	6	μs	
dV/dt	Voltage Transient Ruggedness (Note 2)	ess (Note 2)		V/ns	
$T_J$	Operating Junction Temperature		-55 to +175	°C	
T <sub>stg</sub>	Storage Temperature Range	Storage Temperature Range		°C	
TL	Maximum Lead Temp. for soldering Purposes	d Temp. for soldering Purposes, 1/8" from case for 5 s		°C	

#### THERMAL CHARACTERISTICS

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$ (IGBT)	Thermal Resistance, Junction to Case	-	0.17	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	0.32	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

### PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Pacing Type	Qty per Tube
FGY120T65SPD	FGY120T65SPD-F085	TP-247	Tube	30ea

<sup>1.</sup> Limited by bondwire 2.  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_{CE}$  = 378 A, Inductive Load

#### ELECTRICAL CHARACTERISTICS OF THE IGBT T<sub>.1</sub> = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
OFF CHAR	ACTERISTICS	•				
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	650	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	-	0.6	_	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0 V	-	-	40	μА
I <sub>GES</sub>	G-E Leakage Current	V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0 V	-	-	± 250	nA
ON CHARA	CTERISTICS	•			•	
V <sub>GE(th)</sub>	G-E Threshold Voltage	I <sub>C</sub> = 120 mA, V <sub>CE</sub> = V <sub>GE</sub>	4.2	5.4	6.2	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 120 A, V <sub>GE</sub> = 15 V	_	1.5	1.85	V
		I <sub>C</sub> = 120 A <sub>,</sub> V <sub>GE</sub> = 15 V, T <sub>J</sub> = 175°C	_	1.8	-	V
DYNAMIC (	CHARACTERISTICS					
C <sub>ies</sub>	Input Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$	-	6810	-	pF
C <sub>oes</sub>	Output Capacitance	f = 1 MHz	-	440	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	1	-	50	-	pF
R <sub>G</sub>	Internal Gate Resistance	f = 1 MHz	_	3	-	Ω
SWITCHING	G CHARACTERISTICS					
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{CC}$ = 400 V, $I_{C}$ = 120 A, $R_{G}$ = 5 $\Omega$ , $V_{GE}$ = 15 V,	-	53	-	ns
T <sub>r</sub>	Rise Time	Inductive Load, T <sub>J</sub> = 25°C	-	134	-	ns
T <sub>d(off)</sub>	Turn-Off Delay Time		_	102	-	ns
T <sub>f</sub>	Fall Time		_	115	-	ns
$E_{on}$	Turn-On Switching Loss		_	6.8	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		_	3.5	-	mJ
E <sub>ts</sub>	Total Switching Loss		-	10.3	-	mJ
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 120 \text{ A}, R_{G} = 5 \Omega,$	-	50	-	ns
T <sub>r</sub>	Rise Time	V <sub>GE</sub> = 15 V, Inductive Load, T <sub>J</sub> = 175°C	-	133	-	ns
T <sub>d(off)</sub>	Turn-Off Delay Time	7	-	109	-	ns
T <sub>f</sub>	Fall Time	1	-	138	-	ns
E <sub>on</sub>	Turn-On Switching Loss	7	-	9.8	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss	7	-	4.0	-	mJ
E <sub>ts</sub>	Total Switching Loss	1	-	13.8	-	mJ
Qg	Total Gate Charge	V <sub>CE</sub> = 400 V, I <sub>C</sub> = 120 A, V <sub>GE</sub> = 15 V	-	162	243	nC
Q <sub>ge</sub>	Gate to Emitter Charge	1	_	49	-	nC
Q <sub>gc</sub>	Gate to Collector Charge	7	_	47	_	nC

# **ELECTRICAL CHARACTERISTICS OF THE DIODE** $T_J$ = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Units
$V_{FM}$	Diode Forward Voltage	I <sub>F</sub> = 120 A	T <sub>J</sub> = 25°C	-	1.3	1.6	V
			T <sub>J</sub> = 175°C	-	1.2	-	
E <sub>rec</sub>	Reverse Recovery Energy	$V_{CE} = 400V, I_F = 120 A,$	T <sub>J</sub> = 25°C	-	450	-	μJ
		dI <sub>F</sub> /dt = 1000 A/μs	T <sub>J</sub> = 175°C	-	3000	-	
T <sub>rr</sub>	Diode Reverse Recovery Time		T <sub>J</sub> = 25°C	-	123	-	ns
			T <sub>J</sub> = 175°C	-	240	-	
Q <sub>rr</sub>	Diode Reverse Recovery Charge		T <sub>J</sub> = 25°C	-	2.8	-	μС
			T <sub>J</sub> = 175°C	-	12.2	_	

#### TYPICAL PERFORMANCE CHARACTERISTICS

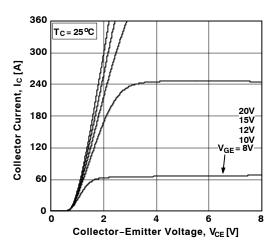


Figure 1. Typical Output Characteristics

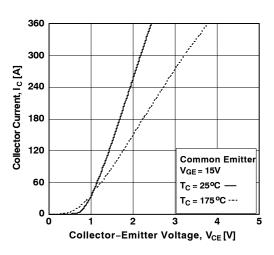


Figure 3. Typical Saturation Voltage Characteristics

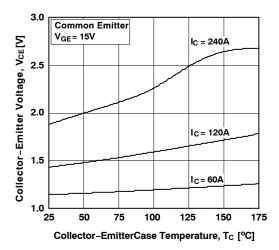


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

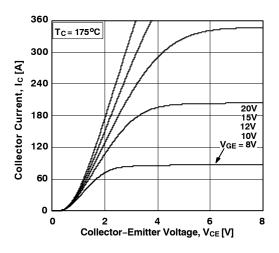


Figure 2. Typical Output Characteristics

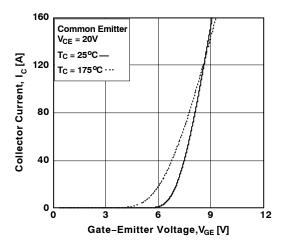


Figure 4. Transfer Characteristics

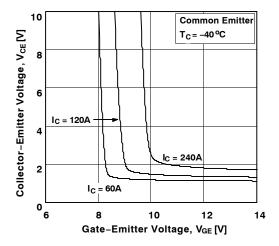


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)

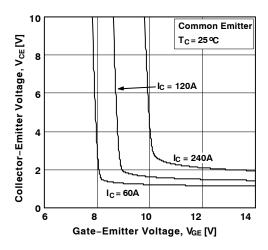


Figure 7. Saturation Voltage vs.  $V_{\text{GE}}$ 

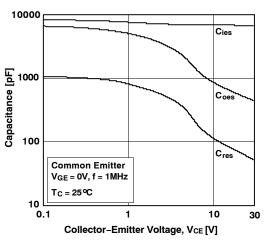


Figure 9. Capacitance Characteristics

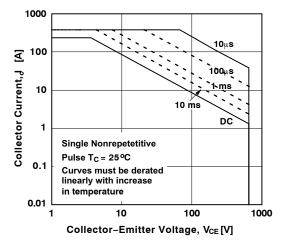


Figure 11. SOA Characteristics

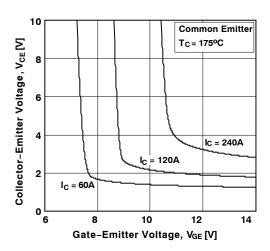


Figure 8. Saturation Voltage vs.  $V_{\text{GE}}$ 

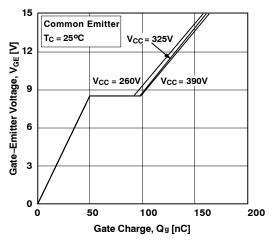


Figure 10. Gate charge Characteristics

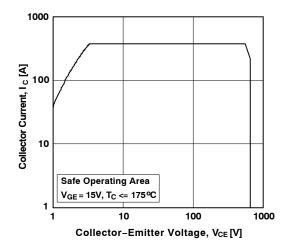


Figure 12. Turn off Switching SOA Characteristics

#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)

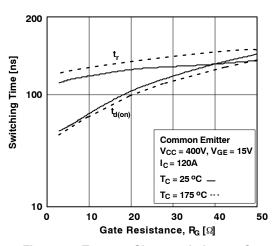


Figure 13. Turn-on Characteristics vs. Gate Resistance

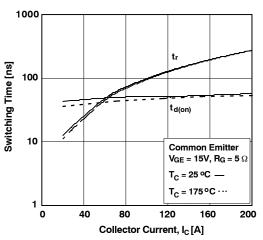


Figure 15. Turn-on Characteristics vs. Collector Current

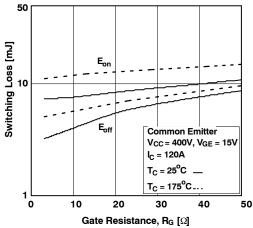


Figure 17. Switching Loss vs Gate Resistance

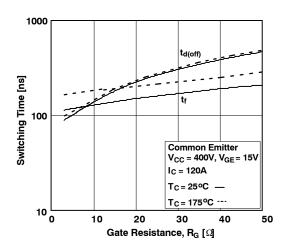


Figure 14. Turn-off Characteristics vs. Gate Resistance

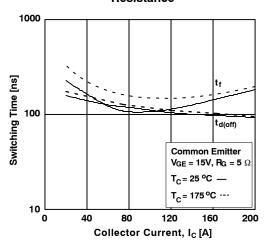


Figure 16. Turn-off Characteristics vs. Collector Current

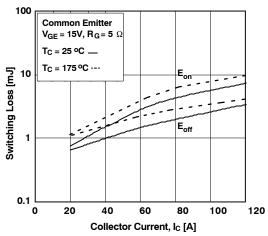


Figure 18. Switching Loss vs Collector Current

#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)

10000

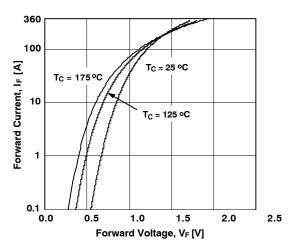
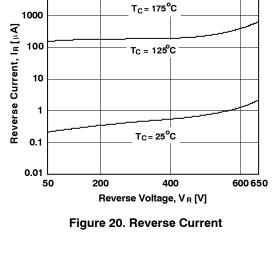


Figure 19. Forward Characteristics



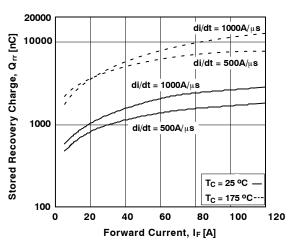


Figure 21. Stored Charge

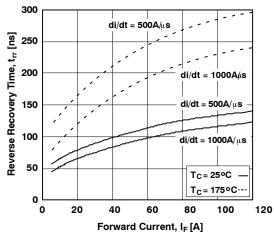


Figure 22. Reverse Recovery Time

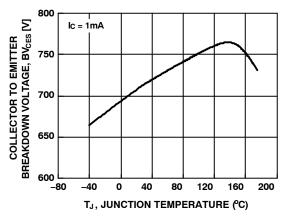


Figure 23. Collector to Emitter Breakdown Voltage vs. Junction Temperature

## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

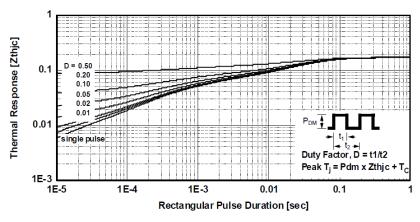


Figure 24. Transient Thermal Impedance of IGBT

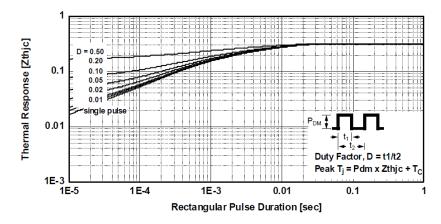
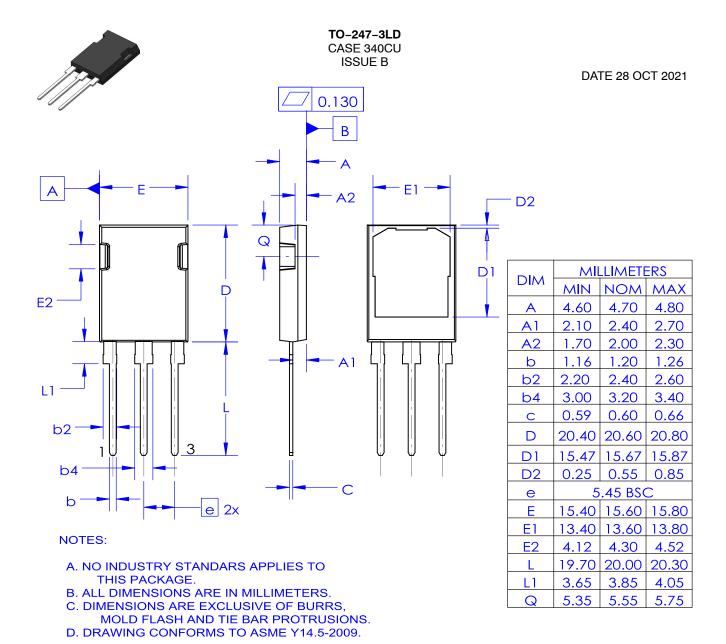


Figure 25. Transient Thermal Impedance of Diode





# GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code

A = Assembly Site Code Y = Year

WW = Work WeekZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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